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Mönsterkort –

Provning av material för mönsterkort, mönsterkort och kretskort –

Del 2-719: Provning av material för mönsterkort och liknande –

Mätning av relativ permittivitet och förlustfaktor (500 MHz till 10 GHz)

Test methods for electrical materials, printed boards and other interconnection structures and assemblies –

Part 2-719: Test methods for materials for interconnection structures –

Relative permittivity and loss tangent (500 MHz to 10 GHz)

Som svensk standard gäller europastandarden EN 61189-2-719:2016. Den svenska standarden innehåller den officiella engelska språkversionen av EN 61189-2-719:2016.

Nationellt förord

Europastandarden EN 61189-2-719:2016

består av:

- **europastandardens ikraftsättningsdokument**, utarbetat inom CENELEC
- **IEC 61189-2-719, First edition, 2016 - Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-719: Test methods for materials for interconnection structures - Relative permittivity and loss tangent (500 MHz to 10 GHz)**

utarbetad inom International Electrotechnical Commission, IEC.

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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies -
Part 2-719: Test methods for materials for interconnection
structures - Relative permittivity and loss tangent (500 MHz to 10
GHz)
(IEC 61189-2-719:2016)

Méthode d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-719: Méthodes d'essai des matériaux
pour structures d'interconnexion - Permittivité relative et
tangente de perte (500 MHz à 10 GHz)
(IEC 61189-2-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen -
Teil 2-719: Prüfverfahren für Materialien von
Verbindungsstrukturen - Relative Permittivität und
Verlustfaktor (500 MHz bis 10 GHz)
(IEC 61189-2-719:2016)

This European Standard was approved by CENELEC on 2016-08-16. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 91/1366/FDIS, future edition 1 of IEC 61189-2-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-2-719:2016.

The following dates are fixed:

- latest date by which the document has to be (dop) 2017-05-16
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2019-08-16
standards conflicting with the
document have to be withdrawn

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Endorsement notice

The text of the International Standard IEC 61189-2-719:2016 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-719: Test methods for materials for interconnection structures –
Relative permittivity and loss tangent (500 MHz to 10 GHz)**

FOREWORD

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International Standard IEC 61189-2-719 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1366/FDIS	91/1380/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)

1 Scope

This part of IEC 61189 specifies a test method of relative permittivity and loss tangent of printed board and assembly materials, expected to be determined 2 to 10 of relative permittivity and 0,001 to 0,050 of loss tangent at 500 MHz to 10 GHz.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*